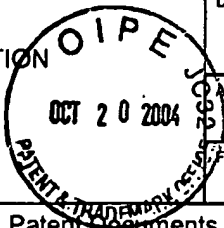


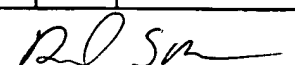


Subst. Form PTO-1449 INFORMATION DISCLOSURE CITATION IN AN APPLICATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) 56247-235 (CSLL-662CP)		Application Number 10/642,315		
				Applicant Sawyer, et al.		Group Art Unit		
				Filing Date 8/15/2003				
U. S. Patent Documents								
EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE	
		6,077,721	06-2000	Fukuda et al.				
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							YES	NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)								
		Copy of International Search Report PCT/US02/00015						
	C1	Moore DF, "Silicon-on insulator material for sensors and accelerometers" Silicon Fabricated Inertial instruments, 9/1-9/5 (December 1996)						
	C2	Syms RRA et al., "Surface tension powered self-assembly of 3D MOEMS devices using DRIE of bonded silicon-on-insulator wafers." IEEE Seminar on Demonstrated Micromachining Technologies for Industry, 1/1-1/6 (March 2000)						
	C3	Yamamoto T et al. "Capacitive accelerometer with high aspect ratio single crystalline silicon microstructure using SOI structure with polysilicon-based interconnect technique." Micro Electro Mechanical Systems, 515-519 (January 2000)						
	C4	Martin A. Schmidt, "Wafer-to-Wafer Bonding for Microstructure Formation", Proceedings of the IEEE, Vol. 86, No. 8, August 1998.						
EXAMINER				DATE CONSIDERED				
				1/23/05				
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy with next communication to applicant.								